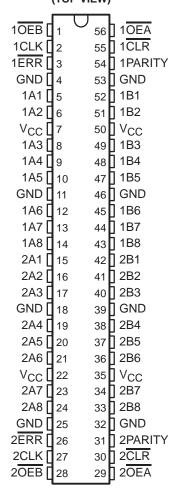
- Members of the Texas Instruments
 Widebus™ Family
- State-of-the-Art EPIC-IIB™ BiCMOS Design Significantly Reduces Power Dissipation
- Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17
- Typical V_{OLP} (Output Ground Bounce)
 1 V at V_{CC} = 5 V, T_A = 25°C
- Distributed V_{CC} and GND Pin Configuration Minimizes High-Speed Switching Noise
- Flow-Through Architecture Optimizes
 PCB Layout
- High-Drive Outputs (–32-mA I_{OH}, 64-mA I_{OI})
- Parity-Error Flag With Parity Generator/Checker
- Register for Storage of Parity-Error Flag
- Package Options Include Plastic 300-mil Shrink Small-Outline (DL) and Thin Shrink Small-Outline (DGG) Packages and 380-mil Fine-Pitch Ceramic Flat (WD) Package Using 25-mil Center-to-Center Spacings

description

The 'ABT16833 consist of two noninverting 8-bit to 9-bit parity bus transceivers and are designed for communication between data buses. For each transceiver, when data is transmitted from the A bus to the B bus, an odd-parity bit is generated and output on the parity I/O pin (1PARITY or 2PARITY). When data is transmitted from the B bus to the A bus, 1PARITY (or 2PARITY) is configured as an input and combined with the B-input data to generate an active-low error flag if odd parity is not detected.

SN54ABT16833 . . . WD PACKAGE SN74ABT16833 . . . DGG OR DL PACKAGE (TOP VIEW)



The error (1ERR or 2ERR) output is configured as an open-collector output. The B-to-A parity-error flag is clocked into 1ERR (or 2ERR) on the low-to-high transition of the clock (1CLK or 2CLK) input. 1ERR (or 2ERR) is cleared (set high) by taking the clear (1CLR or 2CLR) input low.

The output-enable (OEA and OEB) inputs can be used to disable the device so that the buses are effectively isolated. When both OEA and OEB are low, data is transferred from the A bus to the B bus and inverted parity is generated. Inverted parity is a forced error condition that gives the designer more system diagnostic capability.

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

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description (continued)

The SN54ABT16833 is characterized for operation over the full military temperature range of -55° C to 125° C. The SN74ABT16833 is characterized for operation from -40° C to 85° C.

FUNCTION TABLE

		ı	NPUTS				OUTPU	JT AND I/O		
OEB	OEA	CLR	CLK	Ai Σ OF H	Bi [†] Σ OF H	Α	В	PARITY	ERR‡	FUNCTION
L	Н	Х	Х	Odd Even	NA	NA	Α	L H	NA	A data to B bus and generate parity
Н	L	Н	1	NA	Odd Even	В	NA	NA	H L	B data to A bus and check parity
Х	Х	L	Х	Х	Х	Х	NA	NA	Н	Check error-flag register
н	Н	H L H	No↑ No↑ ↑	X X Odd Even	Х	Z	Z	Z	NC H H L	Isolation§
L	L	Х	Х	Odd Even	NA	NA	Α	H L	NA	A data to B bus and generate inverted parity

NA = not applicable, NC = no change, X = don't care

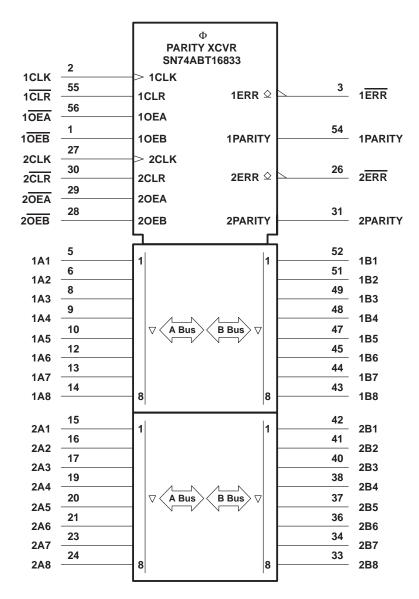


[†]Summation of high-level inputs includes PARITY along with Bi inputs.

[‡]Output states shown assume ERR was previously high.

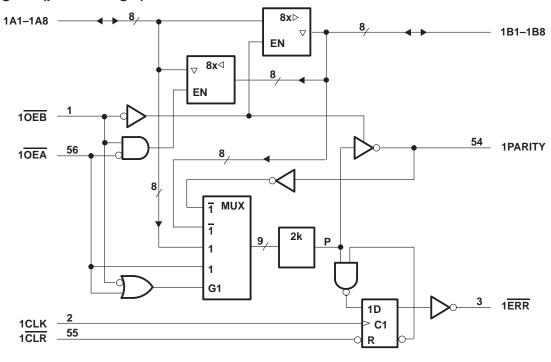
[§] In this mode, ERR (when clocked) shows inverted parity of the A bus.

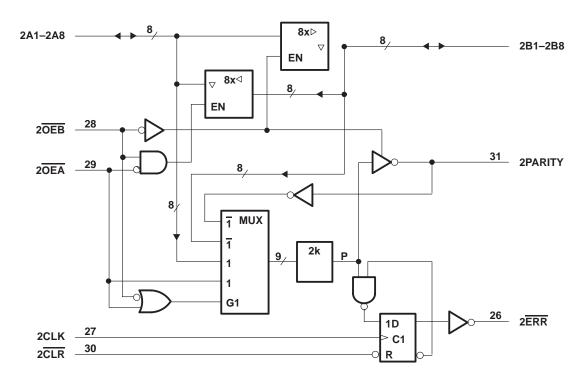
logic symbol†



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



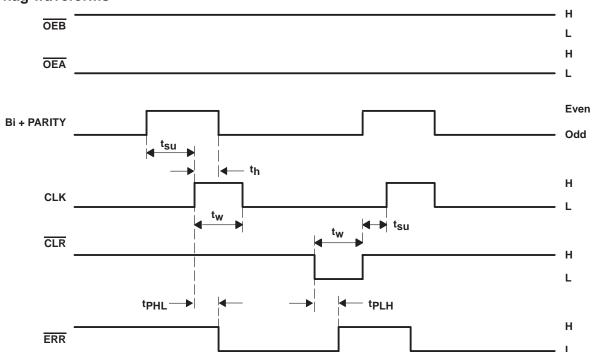


ERROR-FLAG FUNCTION TABLE

INP	UTS	INTERNAL TO DEVICE	OUTPUT PRE-STATE	OUTPUT ERR	FUNCTION
CLR	CLK	POINT P	ERR _{n-1} †	EKK	
Н	↑	Н	Н	Н	
Н	\uparrow	X	L	L	Sample
Н	↑	L	Χ	L	
L	Χ	Х	Х	Н	Clear

[†] State of ERR before changes at CLR, CLK, or point P

error-flag waveforms





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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}	0.5 V to 7 V
Input voltage range, V _I (except I/O ports) (see Note 1)	0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, VO	0.5 V to 5.5 V
Current into any output in the low state, IO: SN54ABT16833	96 mA
SN74ABT16833	128 mA
Input clamp current, I _{IK} (V _I < 0)	–18 mA
Output clamp current, I _{OK} (V _O < 0)	–50 mA
Package thermal impedance, θ _{JA} (see Note 2): DGG package	81°C/W
DL package	74°C/W
Storage temperature range, T _{stq}	-65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions (see Note 3)

			SN54ABT	16833	SN74AB1	16833	UNIT
			MIN	MAX	MIN	MAX	UNIT
Vcc	Supply voltage		4.5	5.5	4.5	5.5	V
VIH	High-level input voltage		2	3	2		V
V _{IL}	Low-level input voltage			0.8		0.8	V
VI	Input voltage		0	Vcc	0	VCC	V
Vон	High-level output voltage	ERR	1	5.5		5.5	V
Іон	High-level output current	Except ERR	2	-24		-32	mA
loL	Low-level output current		20/	48		64	mA
Δt/Δν	Input transition rise or fall rate	Outputs enabled	Q	10		10	ns/V
TA	Operating free-air temperature		-55	125	-40	85	°C

NOTE 3: Unused pins (input or I/O) must be held high or low to prevent them from floating.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

^{2.} The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DA.	DAMETED	TEST CON	IDITIONS	Т	A = 25°C	;	SN54AB1	Г16833	SN74ABT	16833	UNIT
PA	RAMETER	TEST CON	IDITIONS	MIN	TYP†	MAX	MIN	MAX	MIN	MAX	UNII
VIK		$V_{CC} = 4.5 \text{ V},$	I _I = -18 mA			-1.2		-1.2		-1.2	V
		$V_{CC} = 4.5 \text{ V},$	$I_{OH} = -3 \text{ mA}$	2.5	3		2.5				
\ \/a	All outputs	$V_{CC} = 5 V$,	$I_{OH} = -3 \text{ mA}$	3	3.4		3		3		V
VOH	except ERR	V _{CC} = 4.5 V	I _{OH} = -24 mA				2				V
		VCC = 4.5 V	$I_{OH} = -32 \text{ mA}$	2*	2.7				2		
VOL		V _{CC} = 4.5 V	I _{OL} = 24 mA		0.25	0.55		0.55			V
VOL		VCC = 4.5 V	I _{OL} = 64 mA		0.3	0.55*				0.55	V
V _{hys}					100			4			mV
ІОН	ERR	$V_{CC} = 4.5 \text{ V},$	V _{OH} = 5.5 V			20		20		20	μΑ
l _{off}	_	$V_{CC} = 0$, $V_I \text{ or } V_O \le 4.5 \text{ V}$				±100		14°		±100	μΑ
ICEX	Outputs high	$V_{CC} = 5.5 \text{ V},$	$V_0 = 5.5 \text{ V}$			50	4	50		50	μΑ
1.	Control inputs	Vcc = 5.5 V, V _I = V	oo or GND			±1	35	±1		±1	μА
¹ 1	A or B ports	VCC = 5.5 V, V = V	CC or GIAD			±100	90	±100		±100	μΑ
IIL	A or B ports	$V_{CC} = 0$,	$V_I = GND$			- 50	Y'd	- 50		-50	μΑ
lo [‡]		$V_{CC} = 5.5 \text{ V},$	$V_0 = 2.5 \text{ V}$	-50	-100	-180	-50	-180	-50	-180	mA
I _{OZH} §		V _{CC} =5.5 V,	$V_0 = 2.7 \text{ V}$			50		50		50	μΑ
IOZL§		$V_{CC} = 5.5 \text{ V},$	V _O = 0.5 V			- 50		- 50		- 50	μΑ
		V _{CC} = 5.5 V,	Outputs high		1.5	2		2		2	
Icc	A or B ports	$I_{O} = 0$,	Outputs low		28	36		36		36	mA
		$V_I = V_{CC}$ or GND	Outputs disabled		1	2		2		2	
ΔICC¶	$V_{CC} = 5.5 \text{ V}$, One input at 3.4 V, Other inputs at V_{CC} or GND				50		50		50	μА	
Ci	Control inputs	V _I = 2.5 V or 0.5 V			3						pF
C _{io}	A or B ports	V _O = 2.5 V or 0.5 V			9						pF

^{*} On products compliant to MIL-PRF-38535, this parameter does not apply.

[†] All typical values are at $V_{CC} = 5 \text{ V}$.

[‡] Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

[§] The parameters $I_{\mbox{\scriptsize OZL}}$ and $I_{\mbox{\scriptsize OZL}}$ include the input leakage current.

[¶] This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

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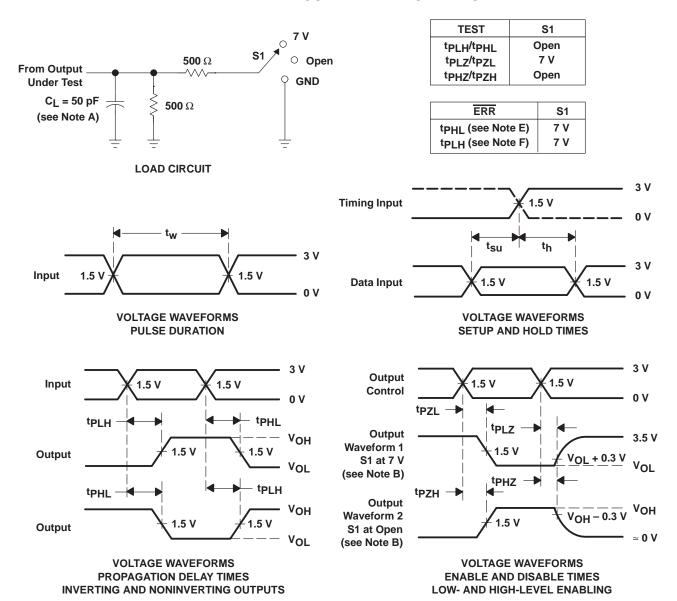
timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

			V _{CC} = T _A = 2	: 5 V, 25°C	SN54AB	Г16833	SN74AB1	16833	UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
t _W	Pulse duration, CLK high or low		3		3,		3		ns
		A port	4.5		4.5	2	4.5		
t _{su}	Setup time before CLK↑	CLR	1		813	4	1		ns
		OEA	5		5		5		
t _h	Hold time after CLK↑	A port or OEA	0		0		0		ns

switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V ₍	CC = 5 V 4 = 25°C	/, ;	SN54AB	T16833	SN74AB1	Г16833	UNIT
	(INFOT)	(001F01)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	
^t PLH	A or B	B or A	1.5	2.5	3.3	1.5	4.2	1.5	4.1	ns
^t PHL	AUIB	BULA	2	3.1	3.9	2	4.5	2	4.3	115
^t PZH	ŌĒ	A or B	2	3.9	4.9	2	5.8	2	5.6	ns
^t PZL	OE	AUIB	2.5	4.3	5.1	2.5	6.2	2.5	6	115
^t PHZ	ŌĒ	A or B	2	3.6	4.5	2	5.5	2	5.4	ns
t _{PLZ}	OE	AUIB	1.5	3	3.8	1.5	4.7	1.5	4.3	113
^t PLH	A or OE	PARITY	2	4.6	5.4	2/	. 7	2	6.7	ne
^t PHL	A or OE	FANITI	2	4.3	5.1	2	6.5	2	6.1	ns
^t PZH	ŌĒ	PARITY	2	3.6	5	0 2	5.8	2	5.7	ns
^t PZL	OE	FARITI	2.5	4.4	5.8	2.5	6.7	2.5	6.5	115
^t PHZ		PARITY	1.5	3.2	4	1.5	4.8	1.5	4.7	
tPLZ	ŌĒ	FARIIT	1.5	2.9	3.7	1.5	4.2	1.5	4.1	ns
t _{PLH}	CLK, CLR	<u></u>	2	3.4	4.2	2	4.8	2	4.6	ns
tPHL	CLK	ERR	2	2.8	3.6	2	4.1	2	3.9	115

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_O = 50 Ω , $t_f \leq$ 2.5 ns, $t_f \leq$ 2.5 ns.
- D. The outputs are measured one at a time with one transition per measurement.
- E. tpHL is measured at 1.5 V.
- F. tpLH is measured at VOL + 0.3 V.

Figure 1. Load Circuit and Voltage Waveforms







.com 27-Sep-2007

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
74ABT16833DGGRE4	ACTIVE	TSSOP	DGG	56	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74ABT16833DGGRG4	ACTIVE	TSSOP	DGG	56	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT16833DGGR	ACTIVE	TSSOP	DGG	56	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT16833DL	ACTIVE	SSOP	DL	56	20	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT16833DLG4	ACTIVE	SSOP	DL	56	20	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT16833DLR	ACTIVE	SSOP	DL	56	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT16833DLRG4	ACTIVE	SSOP	DL	56	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device		Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ABT16833DGGR	TSSOP	DGG	56	2000	330.0	24.4	8.6	15.6	1.8	12.0	24.0	Q1
SN74ABT16833DLR	SSOP	DL	56	1000	330.0	32.4	11.35	18.67	3.1	16.0	32.0	Q1





*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ABT16833DGGR	TSSOP	DGG	56	2000	346.0	346.0	41.0
SN74ABT16833DLR	SSOP	DL	56	1000	346.0	346.0	49.0

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